

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR CHIP CAPABLE OF IMPLEMENTING WIRE BONDING OVER ACTIVE CIRCUITS		
Application Number :			
Date :			
First Named Applicant:		Kun-Chih Wang	
Confirmation Number:			
Attorney Docket Number:		NAUP0559USA	
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Documents being submitted:	Files
us-fee-sheet	NAUP0559-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-declaration	NAUP0559-usdecl.xml us-declaration.dtd us-declaration.xsl
us-power-of-attorney-grant	NAUP0559-uspoat.xml us-power-of-attorney-grant.dtd us-power-of-attorney-grant.xsl
us-assignment	NAUP0559-usassn.xml us-assignment.xsl us-assignment.dtd NAUP0559ASS1.tif NAUP0559ASS2.tif
us-request	NAUP0559-usrequ.xml us-request.dtd us-request.xsl
us-declaration	NAUP0559DEC1.tif
us-declaration	NAUP0559DEC2.tif
application-body	NAUP0559-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd NAUP0559usa-01.tif NAUP0559usa-02.tif

Comments